Embedded Module

Open Standard Module™ - iesy APL OSM-LE

Technical Concept

- ▶ Platform: Intel® Apollo Lake
- ▶ RAM: 4GB
- ▶ Dimension: 45 mm x 45 mm
- ▶ Footprint: OSM Size-L
Land Grid Array (LGA) with 662 contacts
- ▶ Power-Supply: 5V via LGA contacts
- ▶ Software: Windows 10
- ▶ Temperature:
  - > Operating: 0 °C to +85 °C
  - > Storage: -40 °C to +85 °C
- ▶ Features & Interfaces
  - > 4x USB 2.0
  - > 2x USB 3.0
  - > 3x UART
  - > 8 GPIO
  - > 2x SPI
  - > 2x I2C
  - > 1x I2S
  - > 1x SDIO
  - > 1x JTAG
  - > 4x PWM
  - > 1x Camera Interface
  - > 3x PCI
  - > 1x eDP

About OSM™

The Open Standard Modules™ specification was adopted by the SGeT e.V. in 2019. The new standard was developed to meet future requirements in terms of **flexibility**, **scalability**, but also **costs**. OSM™ solder-down modules can be made **individually adapted** to the respective customer requirements. For this purpose, the individual modules can be made **available to the SMT process** by means of tray & reel packaging and processed automatically. The OSM™ series includes in total four different form factors.

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